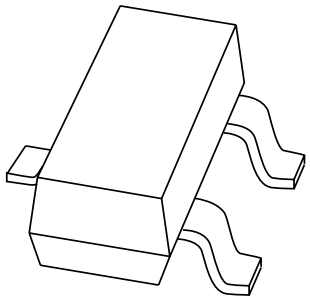
DATA SHEET



PLVA6xxA series
Low-voltage avalanche regulator diodes

Product data sheet
Supersedes data of 1999 May 25

2004 Jan 14

NXP founded by Philips

Low-voltage avalanche regulator diodes PLVA6xxA series

FEATURES

- Very low dynamic impedance at low currents: approximately $\frac{1}{20}$ of conventional series
- Hard breakdown knee
- Low noise: approximately $\frac{1}{10}$ of conventional series
- Total power dissipation: max. 250 mW
- Small tolerances of V_Z
- Working voltage range: nominal 5.00 to 6.80 V
- Non-repetitive peak reverse power dissipation: maximal 30 W.

APPLICATIONS

- Low current, low power, low noise applications
- CMOS RAM back-up circuits
- Voltage stabilizers
- Voltage limiters
- Smoke detector relays.

DESCRIPTION

High performance voltage regulator diodes in small SOT23 plastic SMD packages.

The series consists of PLVA650A to PLVA668A.

MARKING

TYPE NUMBER	MARKING CODE(1)
PLVA650A	*9A
PLVA653A	*9B
PLVA656A	*9C
PLVA659A	*9D
PLVA662A	*9E
PLVA665A	*9F
PLVA668A	*9G

Note

1. * = p: Made in Hong Kong.
   * = t: Made in Malaysia.
   * = W: Made in China.

PINNING

PIN	DESCRIPTION
1	anode
2	not connected
3	cathode

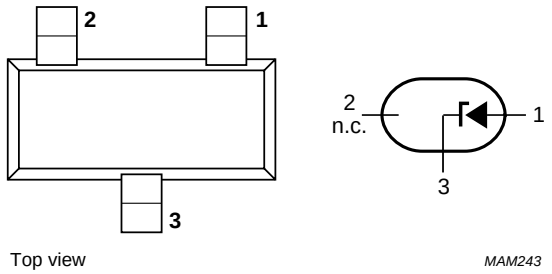


Fig.1 Simplified outline (SOT23) and symbol.

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
PLVA6xxA	–	plastic surface mounted package; 3 leads	SOT23

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I_F	continuous forward current		–	250	mA
I_{ZRM}	repetitive peak working current	t_p = 100 μs; δ = 10%	–	250	mA
P_{ZSM}	non-repetitive peak reverse power dissipation	t_p = 100 μs; T_j = 150 °C	–	30	W
P_{tot}	total power dissipation	T_{amb} = 25 °C; note 1	–	250	mW
T_{stg}	storage temperature		−65	+150	°C
T_j	junction temperature		–	150	°C

Note

1. Device mounted on an FR4 printed circuit-board.

ELECTRICAL CHARACTERISTICS

T_j = 25 °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_F	forward voltage	I_F = 10 mA	–	–	0.9	V
V_Z	working voltage	I_Z = 250 μA				
	PLVA650A		4.80	5.00	5.20	V
	PLVA653A		5.10	5.30	5.50	V
	PLVA656A		5.40	5.60	5.80	V
	PLVA659A		5.70	5.90	6.10	V
	PLVA662A		6.00	6.20	6.40	V
	PLVA665A		6.30	6.50	6.70	V
	PLVA668A		6.60	6.80	7.00	V
V_Z	working voltage	I_Z = 10 μA				
	PLVA650A		–	4.30	–	V
	PLVA653A		–	5.20	–	V
	PLVA656A		–	5.51	–	V
	PLVA659A		–	5.85	–	V
	PLVA662A		–	6.19	–	V
	PLVA665A		–	6.49	–	V
	PLVA668A		–	6.80	–	V
R_Z	dynamic resistance	1 kHz superimposed;				
	PLVA650A	I_{ZAC} is 10% of I_{ZDC}; I_Z = 250 μA	–	–	700	Ω
	PLVA653A		–	–	250	Ω
	PLVA656A to PLVA668A		–	–	100	Ω
S_Z	temperature coefficient	I_Z = 250 μA				
	PLVA650A		–	0.20	–	mV/K
	PLVA653A		–	1.60	–	mV/K
	PLVA656A		–	1.90	–	mV/K
	PLVA659A		–	2.40	–	mV/K
	PLVA662A		–	2.65	–	mV/K
	PLVA665A		–	2.90	–	mV/K
	PLVA668A		–	3.40	–	mV/K
I_R	reverse current	V_R = 80% V_Z nominal				
	PLVA650A		–	–	20000	nA
	PLVA653A		–	–	5000	nA
	PLVA656A		–	–	1000	nA
	PLVA659A		–	–	500	nA
	PLVA662A		–	–	100	nA
	PLVA665A		–	–	50	nA
	PLVA668A		–	–	10	nA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_R	reverse current	V_R = 50% V_Z nominal				
	PLVA650A		–	34	–	nA
	PLVA653A		–	22	–	nA
	PLVA656A		–	1.1	–	nA
	PLVA659A		–	0.9	–	nA
	PLVA662A		–	0.9	–	nA
	PLVA665A		–	0.9	–	nA
	PLVA668A		–	0.8	–	nA
I_R	reverse current	V_R = 90% V_Z nominal				
	PLVA650A		–	21	–	μA
	PLVA653A		–	3.5	–	μA
	PLVA656A		–	1.3	–	μA
	PLVA659A		–	1.0	–	μA
	PLVA662A		–	0.05	–	μA
	PLVA665A		–	0.04	–	μA
	PLVA668A		–	0.006	–	μA
ΔV_Z	line regulation					
	PLVA659A to PLVA668A	I_{LO} = 10 μA; I_{HI} = 1 mA	–	–	0.1	V
	PLVA656A	I_{LO} = 50 μA; I_{HI} = 1 mA	–	–	0.1	V
	PLVA650A	I_{LO} = 100 μA; I_{HI} = 1 mA	–	–	0.4	V
	PLVA653A	I_{LO} = 100 μA; I_{HI} = 1 mA	–	–	0.2	V
V_n	noise voltage density	f = 1 kHz; B = 1 kHz; I_Z = 250 μA	–	–	1.0	$\frac{\mu V}{\sqrt{Hz}}$

THERMAL CHARACTERISTICS

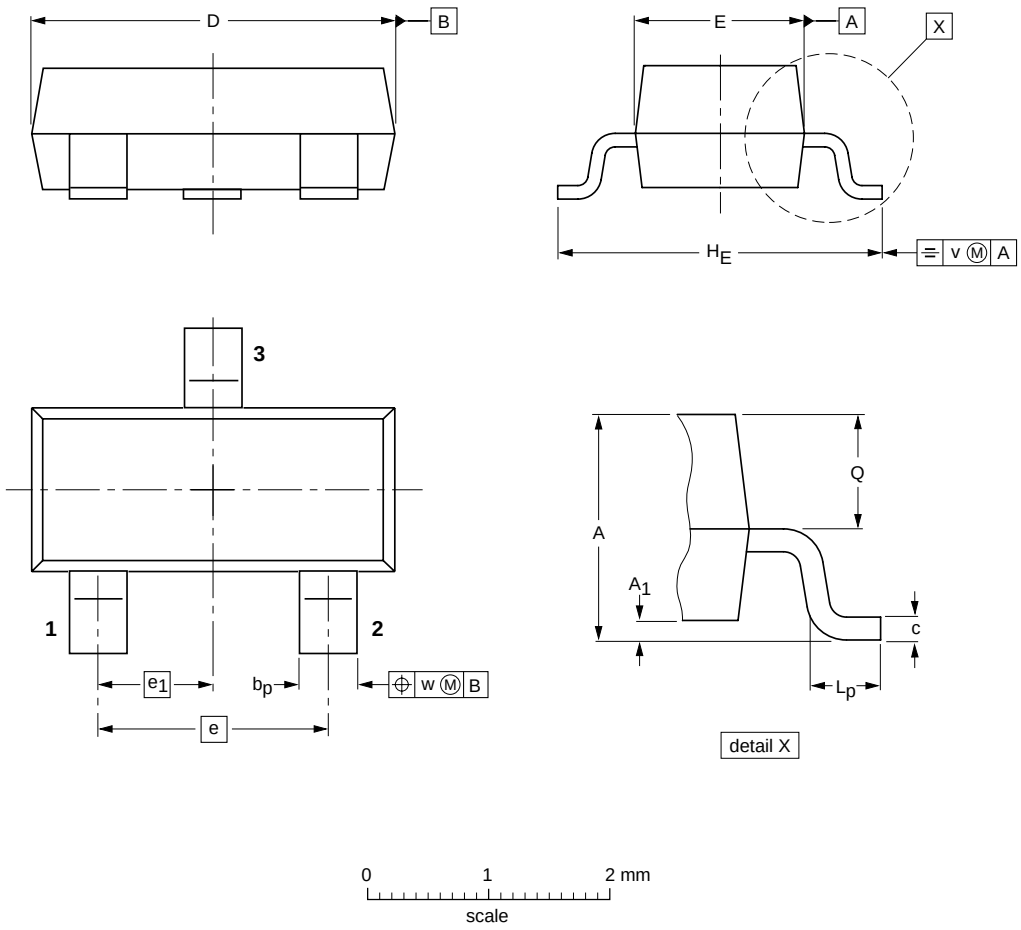
SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j\text{-}tp)}$	thermal resistance from junction to tie-point		330	K/W
$R_{th(j\text{-}a)}$	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Device mounted on an FR4 printed circuit-board.

PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads **SOT23**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1 max.	b_p	c	D	E	e	e_1	H_E	L_p	Q	v	w
mm	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT23		TO-236AB				~~04-11-04~~ 06-03-16

DATA SHEET STATUS

DOCUMENT STATUS[1]	PRODUCT STATUS[2]	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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